

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	54096	(Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L16	36495	15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L17	12708	16 and (metallizat\$6 or pad or bondpad)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L18	10472	17 and (@ad<="20010921" or @rlad<="200140921")	US-PGPUB; USPAT	OR	ON	2005/07/19 15:57
L19	3658	18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6))	US-PGPUB; USPAT	OR	ON	2005/07/19 16:31
L20	3507	19 and (substrate or wafer or semiconductor or base)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:55
L21	9625	17 and (@ad<="20010921" or @rlad<="20010921")	US-PGPUB; USPAT	OR	ON	2005/07/19 15:58
L22	3150	20 and 21	US-PGPUB; USPAT	OR	ON	2005/07/19 15:58
L23	4148	(Cu or copper) same (((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6)))	US-PGPUB; USPAT	OR	ON	2005/07/19 16:32
L24	444	22 and 23	US-PGPUB; USPAT	OR	ON	2005/07/19 16:32

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L15	54096	(Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L16	36495	15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L17	12708	16 and (metallizat\$6 or pad or bondpad)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L18	10472	17 and (@ad<="20010921" or @rlad<="200140921")	US-PGPUB; USPAT	OR	ON	2005/07/19 15:57
L19	3658	18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6))	US-PGPUB; USPAT	OR	ON	2005/07/19 15:48
L20	3507	19 and (substrate or wafer or semiconductor or base)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:55
L21	9625	17 and (@ad<="20010921" or @rlad<="20010921")	US-PGPUB; USPAT	OR	ON	2005/07/19 15:58
L22	3150	20 and 21	US-PGPUB; USPAT	OR	ON	2005/07/19 15:58

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L15	54096	(Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L16	36495	15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L17	12708	16 and (metallizat\$6 or pad or bondpad)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:43
L18	10472	17 and (@ad<="20010921" or @rlad<="200140921")	US-PGPUB; USPAT	OR	ON	2005/07/19 15:44
L19	3658	18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6))	US-PGPUB; USPAT	OR	ON	2005/07/19 15:48
L20	3507	19 and (substrate or wafer or semiconductor or base)	US-PGPUB; USPAT	OR	ON	2005/07/19 15:50

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	37953	(Cu or copper) and (stress\$6 or strain\$6) and (solder\$6 or bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/19 15:29
L4	56440	(Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/19 15:30
L5	11838	((Cu or copper) same (stress\$6 or strain\$6 or compress\$6)) and (solder\$6 or bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/19 15:30
L6	7478	5 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/19 15:32
L8	55	6 and (metallizat\$6 or pad or bondpad)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/19 15:33